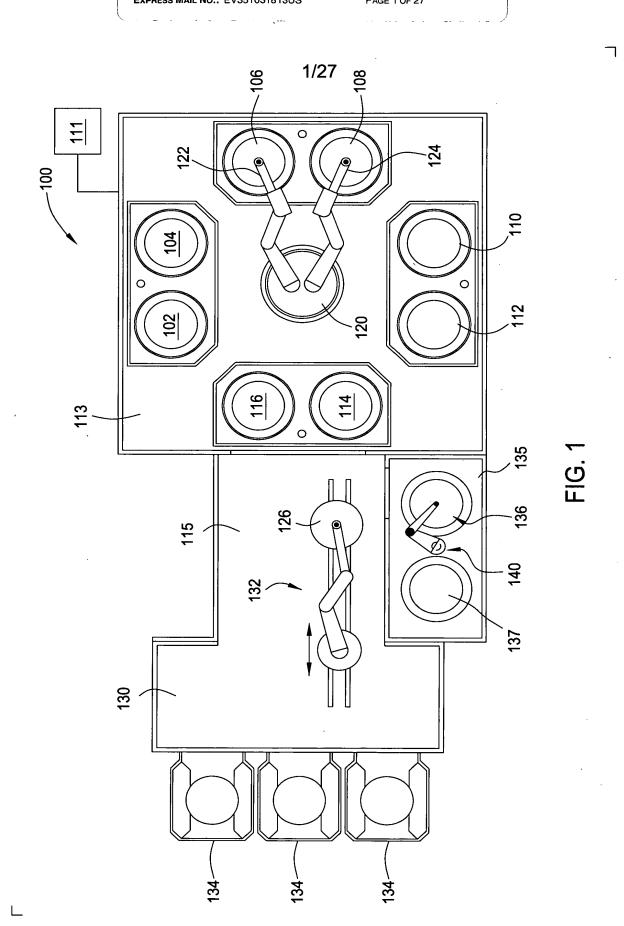
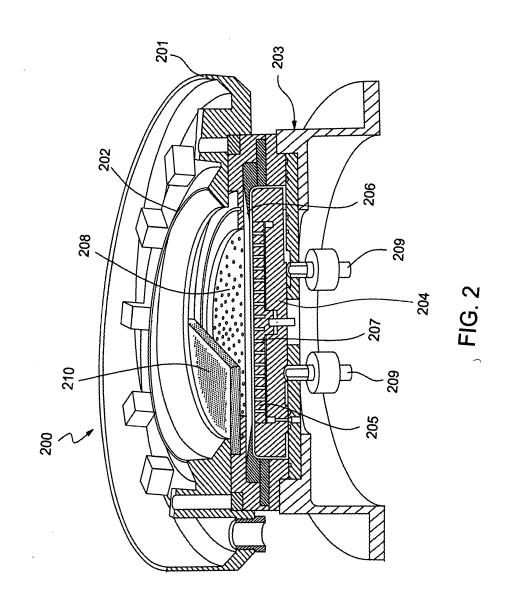
ATTY DKT. NO.: AMAT/7669.P1/CMP/ECP/RKK
U.S. SERIAL NO.: UNKNOWN CONF. NO.: UNKNOWN
FILED: HEREWITH
APPLICANT: APPLIED MATERIALS
TITLE: MULTI-CHEMISTRY PLATING SYSTEM
INVENTOR: MICHAEL X. YANG, ET AL.
EXPRESS MAIL NO.: EV351031813US PAGE 1 OF 27



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U.S. SERIAL NO.: UNKNOWN
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APPLICANT: APPLIED MATERIALS
TITLE: MULTI-CHEMISTRY PLATING SYSTEM
MICHAEL X. YANG, ET AL.
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ATTY DKT. NO.: AMAT/7669.P1/CMP/ECP/RKK
U.S. SERIAL NO.: UNKNOWN CONF. NO.: UNKNOWN
FILED: HEREWITH
APPLICANT: APPLIED MATERIALS
TITLE: MULTI-CHEMISTRY PLATING SYSTEM
INVENTOR: MICHAEL X. YANG, ET AL.
EXPRESS MAIL NO.: EV/25/10318/13118. EXPRESS MAIL No.: EV351031813US PAGE 3 OF 27

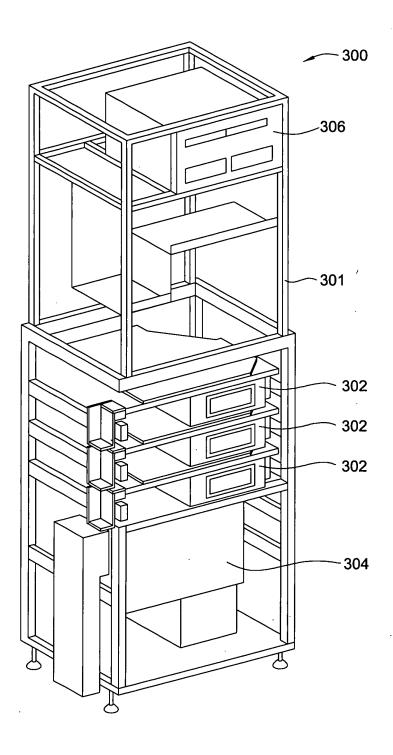
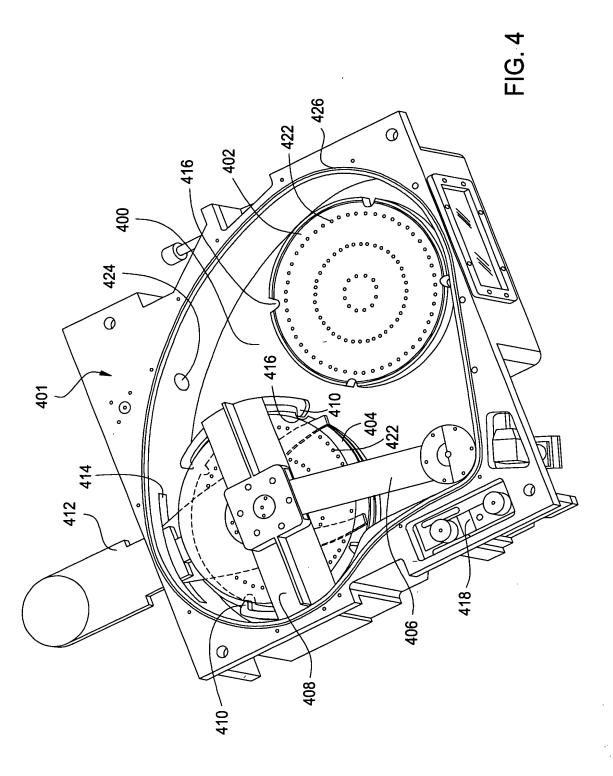


FIG. 3

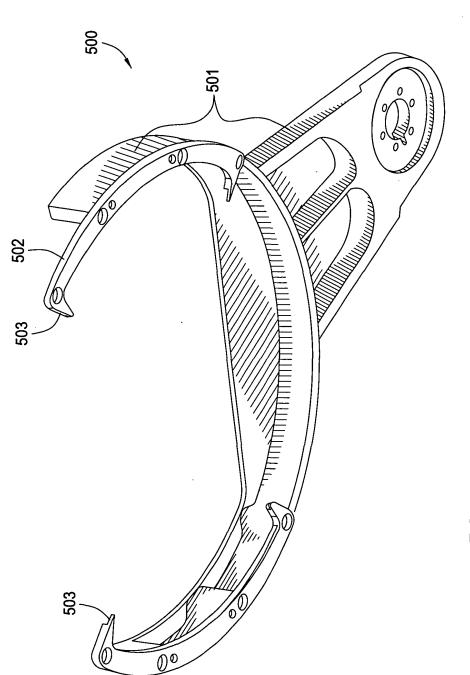
ATTY DKT. NO.: AMAT/7669.P1/CMP/ECP/RKK
U.S. SERIAL NO.: UNKNOWN CONF. NO.: UNKNOWN
FILED: HEREWITH
APPLICANT: APPLIED MATERIALS
TITLE: MULTI-CHEMISTRY PLATING SYSTEM
INVENTOR: MICHAEL X. YANG, ET AL.
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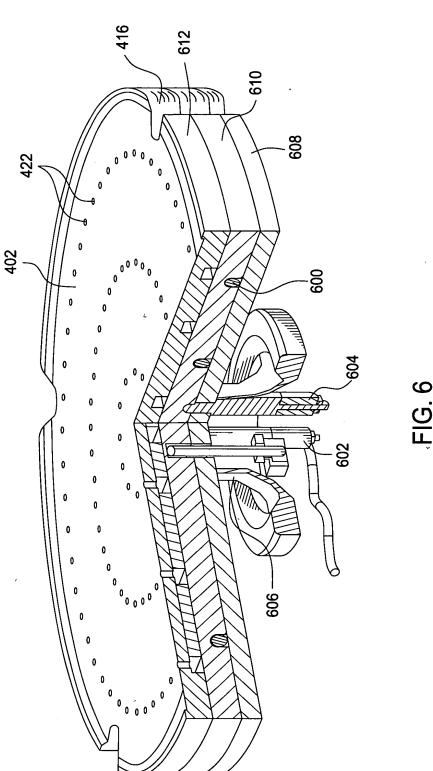
ATTY DKT. NO.: AMAT/7669.P1/CMP/ECP/RKK
U.S. SERIAL NO.: UNKNOWN CONF. NO.: UNKNOWN
FILED: HEREWITH
APPLICANT: APPLIED MATERIALS
TITLE: MULTI-CHEMISTRY PLATING SYSTEM
INVENTOR: MICHAEL X. YANG, ET AL.
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U.S. SERIAL NO.: UNKNOWN CONF. NO.:
FILED: HEREWITH CONF. No.: UNKNOWN

APPLICANT: APPLIED MATERIALS
TITLE: MULTI-CHEMISTRY PLATING SYSTEM
INVENTOR: MICHAEL X. YANG, ET AL.
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U.S. SERIAL NO.: UNKNOWN CONF. NO.:
FILED: HEREWITH CONF. No.: UNKNOWN

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APPLICANT: APPLIED MATERIALS

TITLE: MULTI-CHEMISTRY PLATING SYSTEM
INVENTOR: MICHAEL X. YANG, ET AL.

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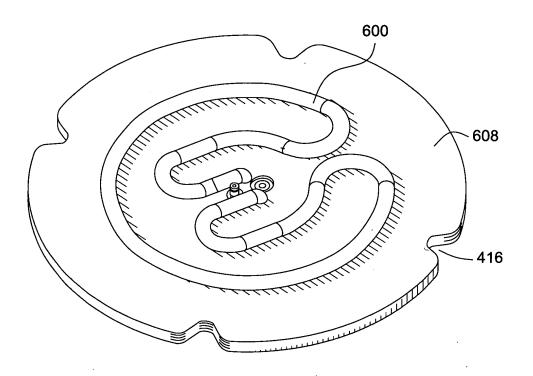
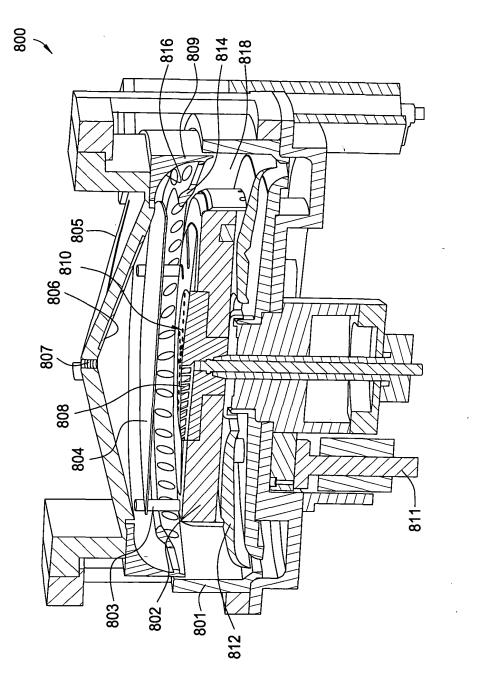


FIG. 7

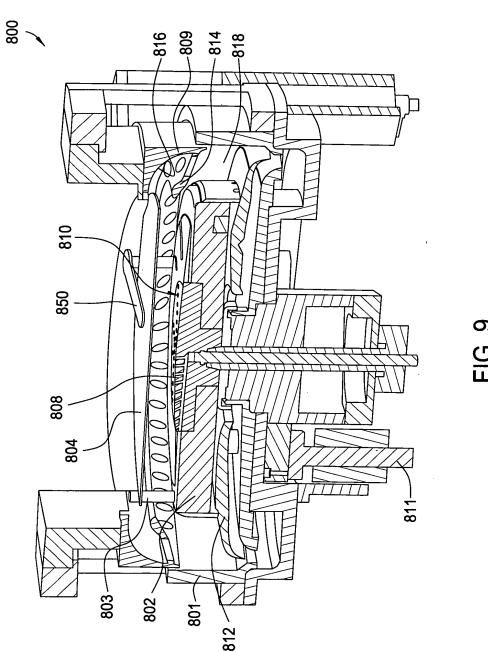
ATTY DKT. NO.: AMAI//669.PI/CMP/ECP/HKK
U.S. SERIAL NO.: UNKNOWN CONF. NO.: UNKNOWN
FILED: HEREWITH
APPLICANT: APPLIED MATERIALS
TITLE: MULTI-CHEMISTRY PLATING SYSTEM
INVENTOR: MICHAEL X, YANG, ET AL. CONF. No.: UNKNOWN

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U.S. SERIAL NO.: UNKNOWN CONF. NO.: UNKNOWN
FILED: HEREWITH
APPLICANT: APPLIED MATERIALS
TITLE: MULTI-CHEMISTRY PLATING SYSTEM
INVENTOR: MICHAEL X. YANG, ET AL.
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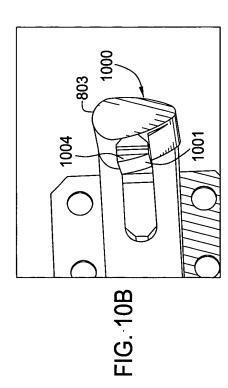
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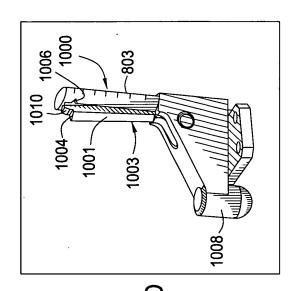


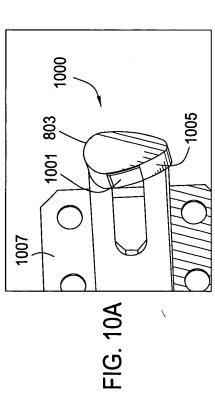
ATTY DKT. NO.: AMAT/7669.P1/CMP/ECP/RKK
U.S. SERIAL NO.: UNKNOWN
FILED: HEREWITH
APPLICANT: APPLIED MATERIALS
TITLE: MULTI-CHEMISTRY PLATING SYSTEM
INVENTOR: MICHAEL X. YANG, ET AL.
EXPRESS MAIL NO.: EV351031813US
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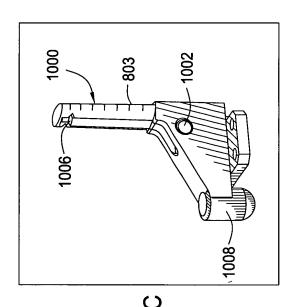
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ATTY DKT. NO..

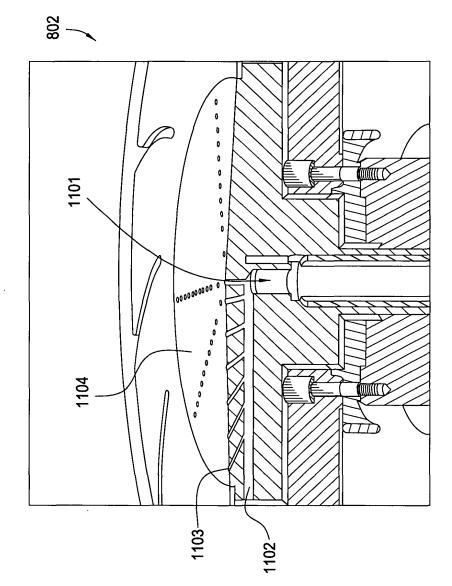
U.S. SERIAL NO.: UNKNOWN CONF. NO.: UNKNOWN HEREWITH

APPLICANT: APPLIED MATERIALS

TITLE: MULTI-CHEMISTRY PLATING SYSTEM MICHAEL X. YANG, ET AL.

PAGE 11 CONF. No.: UNKNOWN

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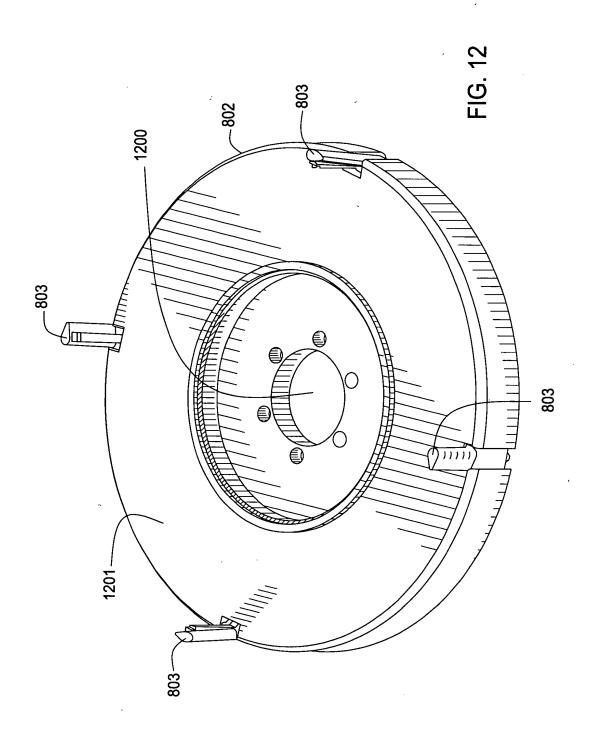
ATTY DKT. NO.: AMAT/7669.P1/CMP/ECP/RKK

U.S. SERIAL NO.: UNKNOWN CONF. NO.: UNKNOWN
FILED: HEREWITH
APPLICANT: APPLIED MATERIALS

TITLE: MULTI-CHEMISTRY PLATING SYSTEM
INVENTOR: MICHAEL X. YANG, ET AL.

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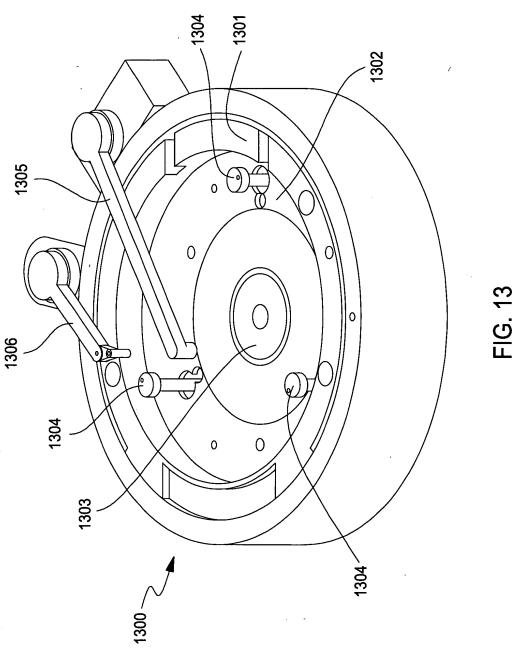
12/27



ATTY DKT. NO.: AMAT/7669.P1/CMP/ECP//RKK
U.S. SERIAL NO.: UNKNOWN CONF. NO.: UNKNO
FILED: HEREWITH
APPLICANT: APPLIED MATERIALS
TITLE: MULTI-CHEMISTRY PLATING SYSTEM
INVENTOR: MICHAEL X. YANG, ET AL.
EXPRESS MAIL NO.: EV351031813US PAGE 13 CONF. No.: UNKNOWN

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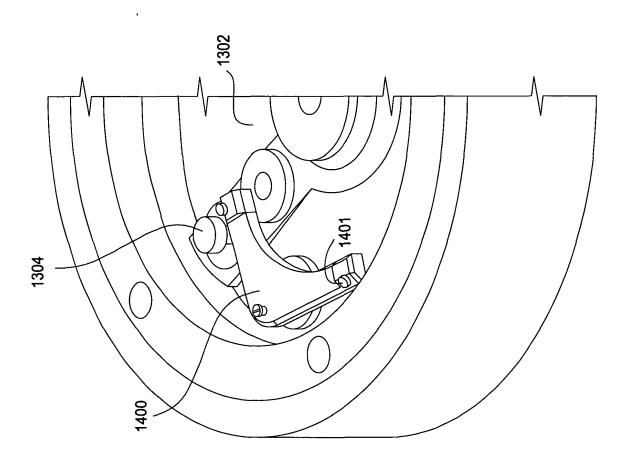


ATTY DKT. NO.: AMAT/7669.P1/CMP/ECP/RKK
U.S. SERIAL NO.: UNKNOWN CONF. NO.: UNKNOWN
FILED: HEREWITH
APPLICANT: APPLIED MATERIALS
TITLE: MULTI-CHEMISTRY PLATING SYSTEM
INVENTOR: MICHAEL X. YANG, ET AL.
EXPRESS MAIL NO.: EV351031813US PAGE 14 OF 2

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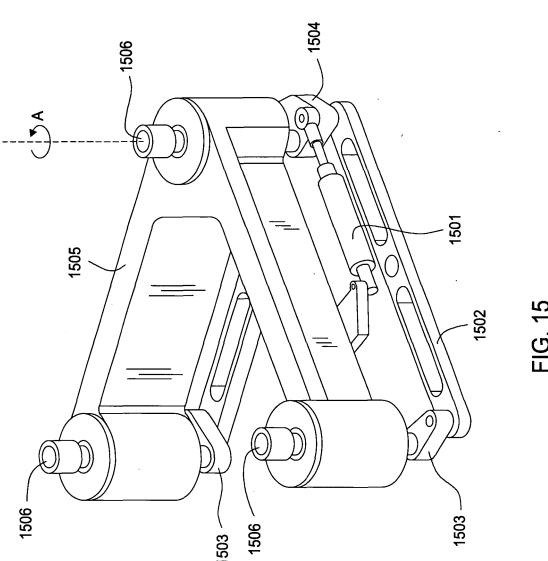
 \neg



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U.S. SERIAL NO.: UNKNOWN CONF. NO.: UNKNOWN
FILED: HEREWITH
APPLICANT: APPLIED MATERIALS
TITLE: MULTI-CHEMISTRY PLATING SYSTEM
INVENTOR: MICHAEL X. YANG, ET AL.
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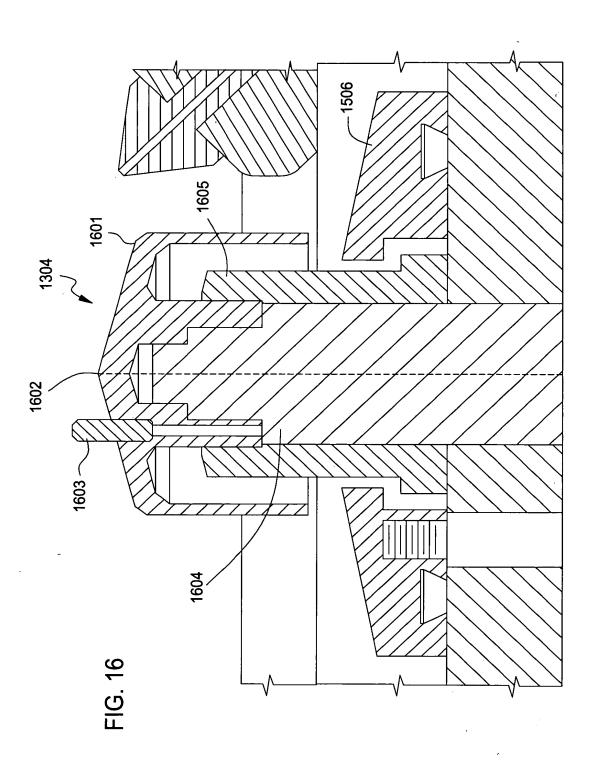
ATTY DKT. No.: AMAT/7669.P1/CMP/ECP/RKK
U.S. SERIAL No.: UNKNOWN CONF. No.: UNKNOWN
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APPLICANT: TITLE: INVENTOR:

APPLIED MATERIALS
MULTI-CHEMISTRY PLATING SYSTEM
MICHAEL X. YANG, ET AL.

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ATTY DKT. No.: AMAT/7669.P1/CMP/ECP/RKK
U.S. SERIAL NO.: UNKNOWN CONF. No.: UNKNOWN
FILED: HEREWITH
APPLICANT: APPLIED MATERIALS
TITLE: MULTI-CHEMISTRY PLATING SYSTEM
INVENTOR: MICHAEL X. YANG, ET AL.
EXPRESS MAIL NO.: EV351031813US PAGE 17 OF 2' PAGE 17 OF 27

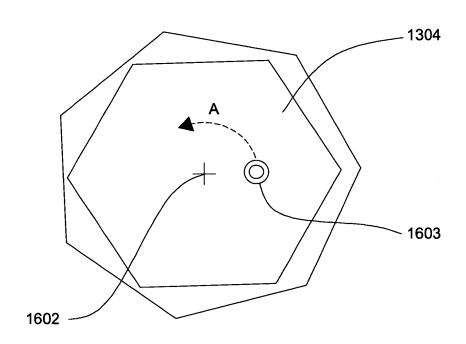
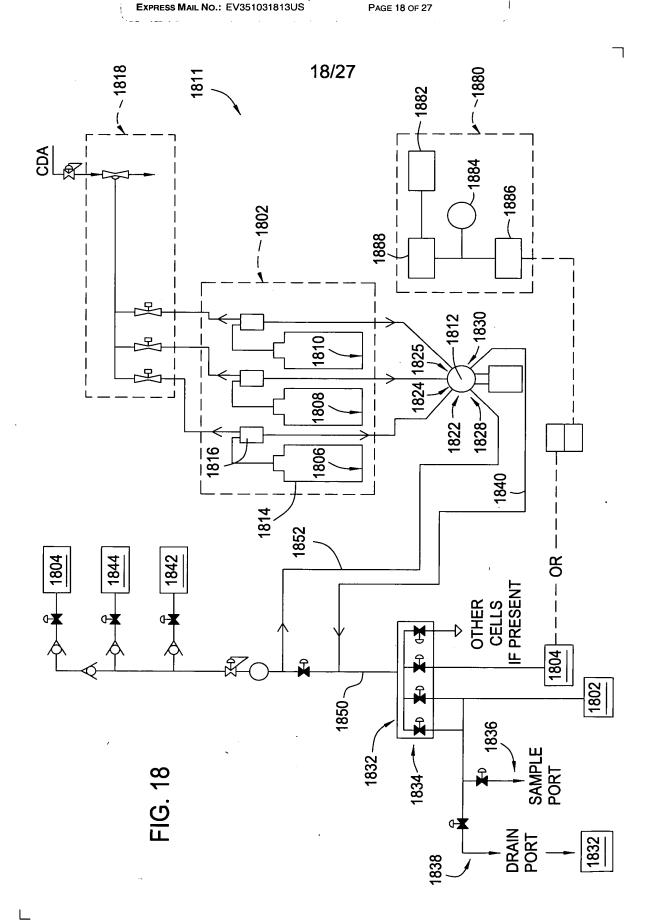


FIG. 17

ATTY DKT. NO.: AMAT/7669.P1/CMP/ECP/RKK
U.S. SERIAL NO.: UNKNOWN CONF. NO.: UNKNOWN
FILED: HEREWITH
APPLICANT: APPLIED MATERIALS
TITLE: MULTI-CHEMISTRY PLATING SYSTEM
INVENTOR: MICHAEL X. YANG, ET AL.
EXPRESS MAIL NO.: EV351031813US PAGE 18 OF 27



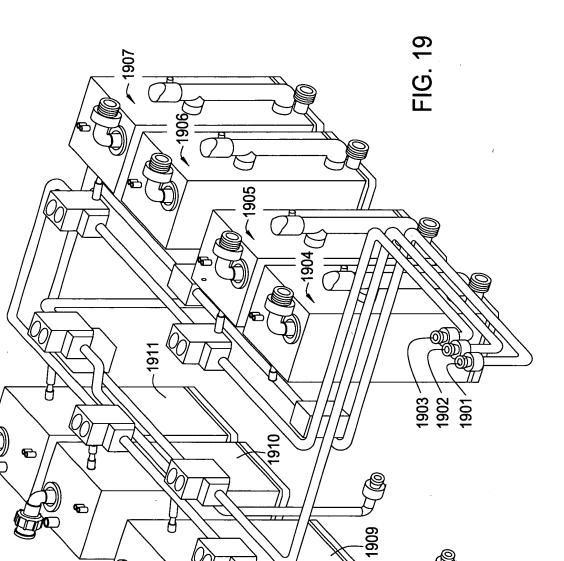
ATTY DKT. NO.: AMAT/7669.P1/CMP/ECP/RKK
U.S. SERIAL NO.: UNKNOWN CONF. NO.: UNKNOWN
FILED: HEREWITH

APPLICANT:

APPLIED MATERIALS
MULTI-CHEMISTRY PLATING SYSTEM
MICHAEL X. YANG, ET AL. TITLE:

INVENTOR: EXPRESS MAIL No.: EV351031813US PAGE 19 OF 27

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ATTY DKT. NO.: AMAT/7669.P1/CMP/ECP/RKK
U.S. SERIAL NO.: UNKNOWN CONF. NO.: UNKNOWN
FILED: HEREWITH
APPLICANT: APPLIED MATERIALS
TITLE: MULTI-CHEMISTRY PLATING SYSTEM
INVENTOR: MICHAEL X. YANG, ET AL.
EXPRESS MAIL NO.: EV351031813US PAGE 20 OF 27

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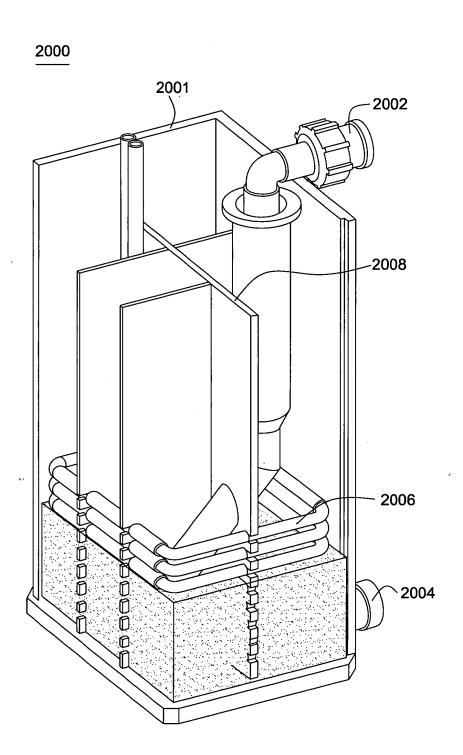
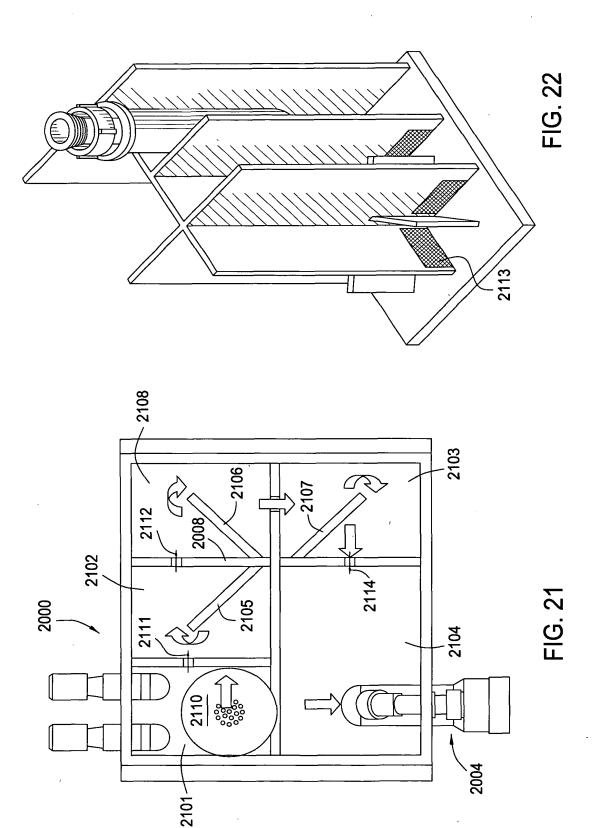


FIG. 20

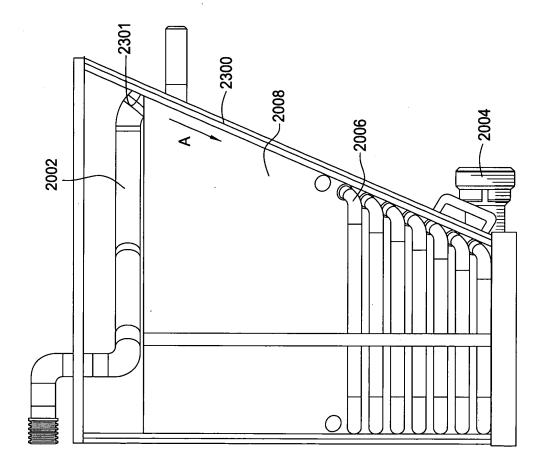
ATTY DKT. NO.: AMAT/7669.P1/CMP/ECP/RKK
U.S. SERIAL NO.: UNKNOWN CONF. NO.: UNKNOWN
FILED: HEREWITH
APPLICANT: APPLIED MATERIALS
TITLE: MULTI-CHEMISTRY PLATING SYSTEM
INVENTOR: MICHAEL X. YANG, ET AL.
EXPRESS MAIL NO.: EV351031813US PAGE 21 OF 27 PAGE 21 OF 27

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ATTY DKT. NO.: AMAT/7669.P1/CMP/ECP/RKK U.S. SERIAL NO.: UNKNOWN CONF. NO. FILED: HEREWITH CONF. No.: UNKNOWN

APPLICANT: APPLIED MATERIALS
TITLE: MULTI-CHEMISTRY PLATING SYSTEM
INVENTOR: MICHAEL X. YANG, ET AL.
EXPRESS MAIL NO.: EV351031813US PAGE 22 PAGE 22 OF 27



ATTY DKT. No.: AMAT/7669.P1/CMP/ECP/RKK

U.S. SERIAL NO.: UNKNOWN CONF. No.: UNKNOWN
HEREWITH
APPLICANT: APPLICE MATERIALS
MULTI-CHEMISTRY PLATING SYSTEM
MICHAEL X. YANG, ET AL.
INVENTOR: EV351031813US PAGE 23 OF 2'

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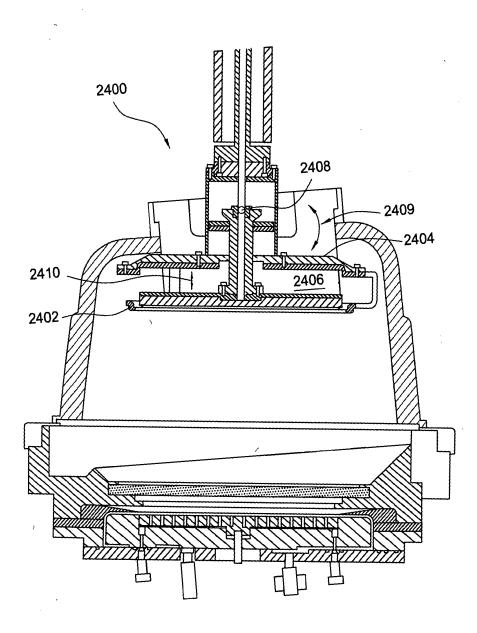


FIG. 24

ATTY DKT. NO.: AMAT/7669.P1/CMP/ECP/RKK
U.S. SERIAL NO.: UNKNOWN CONF. NO.: UNKNOWN
HEREWITH
APPLICANT: MPLICE MATERIALS
MULTI-CHEMISTRY PLATING SYSTEM
MICHAEL X. YANG, ET AL.
EXPRESS MAIL NO.: EV351031813US PAGE 24 OF 2

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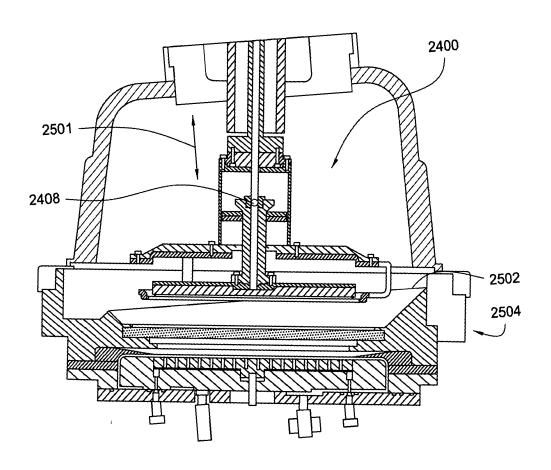


FIG. 25

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ATTY DKT. No.:

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INVENTOR:
INVENTOR:
EXPRESS MAIL NO.:

AMAT/7669.P1/CMP/ECP/RKK

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CONF. NO.: UNKNOWN
HEREWITH
APPLIED MATERIALS
MULTI-CHEMISTRY PLATING SYSTEM
MICHAEL X. YANG, ET AL.
PAGE 25 OF 2 PAGE 25 OF 27

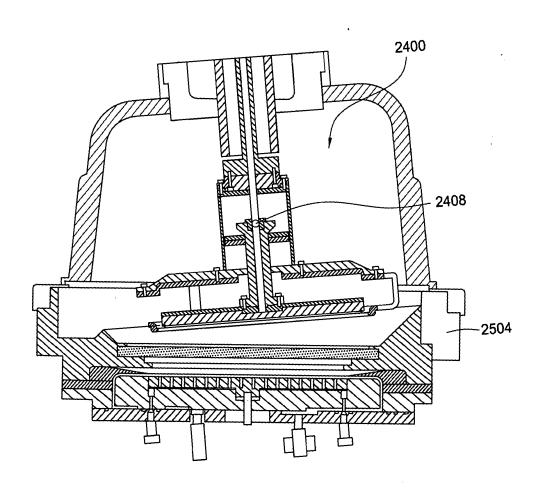


FIG. 26

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ATTY DKT. No.:

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TITLE:
INVENTOR:
EXPRESS MAIL NO.:

AMAT/7669.P1/CMP/ECP/RKK
UNKNOWN
CONF. No.: UNKNOWN
HEREWITH
APPLIED MATERIALS
MULTI-CHEMISTRY PLATING SYSTEM
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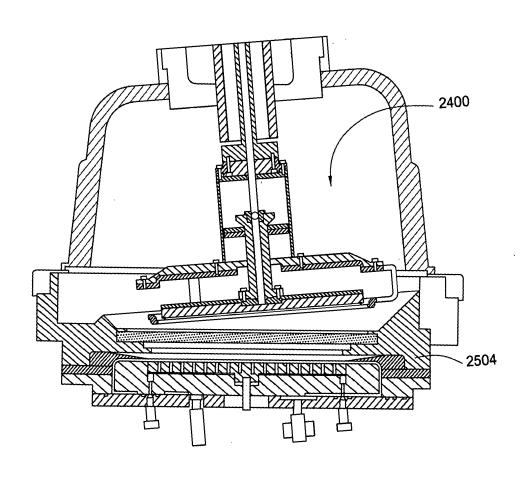


FIG. 27

ATTY DKT. No.:

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U.S. SERIAL No.:

UNKNOWN
CONF. No.: UNKNOW
HEREWITH
APPLICANT:

MULTI-CHEMISTRY PLATING SYSTEM
MICHAEL X. YANG, ET AL.

PAGE 27 CONF. NO.: UNKNOWN

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